

Notice of References Cited	Application/Control No. 10/693,929	Applicant(s)/Patent Under Reexamination KUROSAWA ET AL.	
	Examiner Michelle Estrada	Art Unit 2823	Page 1 of 1

U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-6,165,890	12-2000	Kohl et al.	438/619
	B	US-2002/0090831	07-2002	Yoshida et al.	438/780
	C	US-			
	D	US-			
	E	US-			
	F	US-			
	G	US-			
	H	US-			
	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

FOREIGN PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N					
	O					
	P					
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	R					
	S					
	T					

NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Shick et al., "New Olefinic Interlevel Dielectric Materials for Multi-Chip Modules", 1996, IEEE.
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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.